

Universal Serial Bus Power Controller

FEATURES

- Fully USB Compliant
- Support Four 5V Peripherals and One USB 3.3V Controller
- Separate Power Enables
- 500mA Current Limiting per Channel
- Separate Open Drain Fault Indicator for Each Channel
- 3.3V Output for USB Controller
- Available in 28 Pin Wide Surface Mount and DIP

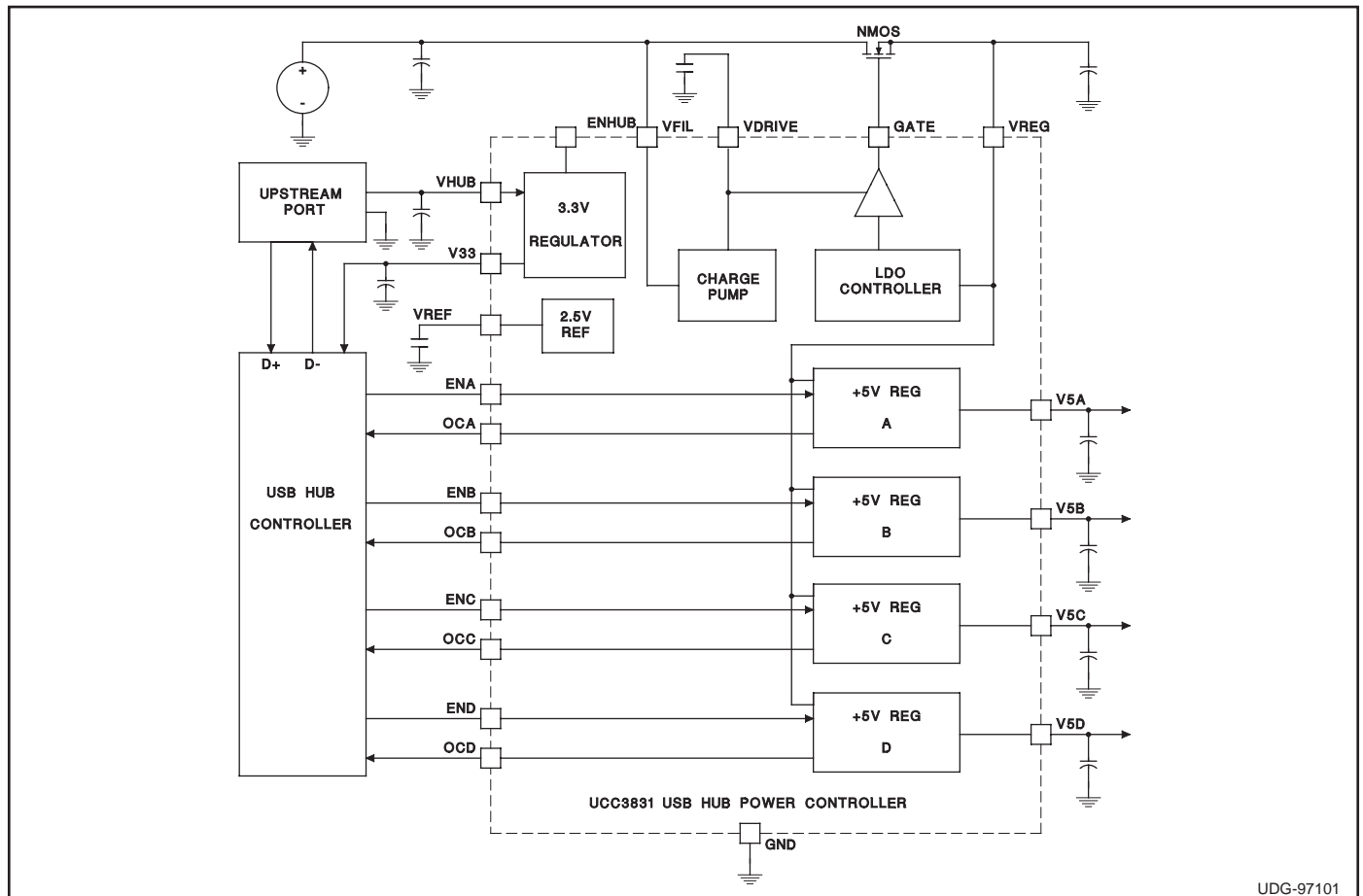
DESCRIPTION

The UCC3831 Power Controller is designed to provide a self powered USB hub with a local 3.3V regulated voltage and four 5V regulated voltages for USB ports. Each of the 5V output ports is individually enabled for optimal port control. Each port also provides an overcurrent fault signal indicating that the port has exceeded a 500mA current limit. The 3.3V linear regulator is used to power the local USB microcontroller. This regulator is protected with a 100mA current limit and has a logic level enable input.

The UCC3831 can be configured to provide USB port power from a loosely regulated voltage such as a Filament voltage internal to a monitor. Pre-regulation is provided by an internal linear regulator controller and one external logic level N-channel MOSFET. The UCC3831 can also be configured without using the pre-regulator stage by connecting the VREG pins to a regulated 5.5V 2A source.

The UCC3831 comes in a 28-pin wide SOIC power package optimized for power dissipation, and is protected by internal over-temperature shutdown mechanism, which disables the outputs should the internal junction temperature exceed 150°C.

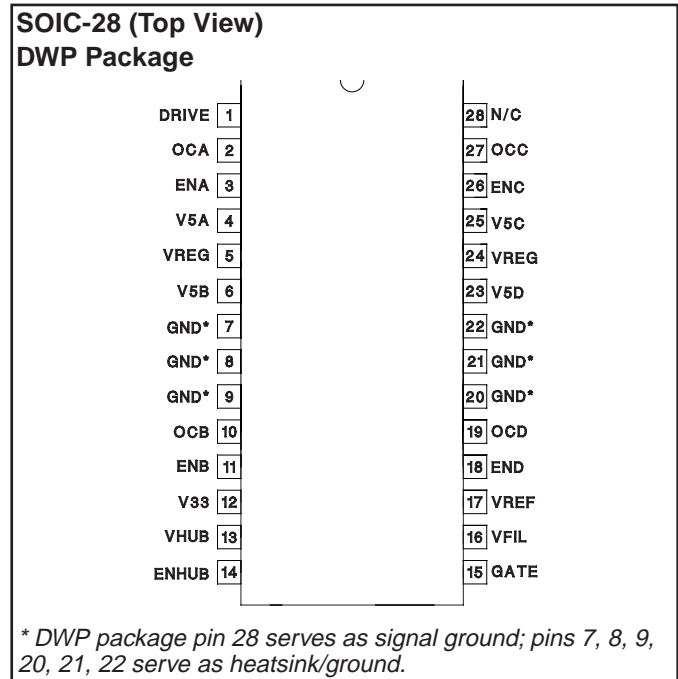
APPLICATION AND BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

VFIL..... 9V
 VCON Supply Voltage 9V
 Logic Inputs (ENA-D, ENHUB)
 Maximum Forced Voltage -0.3V to 7V
 Maximum Forced Current ±1mA
 V33
 Maximum Forced Voltage..... 5V
 Maximum Current 200mA
 V5A-D
 Maximum Voltage..... 9V
 Maximum Current 750mA
 Storage Temperature -65°C to +150°C
 Junction Temperature..... -55°C to +150°C
 Lead Temperature (Soldering, 10 sec.) +300°C
*Unless otherwise indicated, voltages are reference to ground.
 Pulsed is defined as a less than 10% duty cycle with a maximum
 duration of 500µS. Currents are positive into, negative out of the
 specified terminal. All voltages are with respect to ground. Con-
 sult Packaging Section of Databook for thermal limitations and
 considerations of packages.*

CONNECTION DIAGRAM



ELECTRICAL CHARACTERISTICS Unless otherwise specified, T_J = 0°C to 125°C for the UCC3831. VFIL = 6.5V, VHUB = 5V. T_A = T_J.

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|--------------------------------|---|-------|-------|-------|-------|
| Input Supply Currents | | | | | |
| VHUB Supply Current | No External Load on V33 | | 1 | 3 | mA |
| VFIL Supply Current | | | 1 | 3 | mA |
| Reference | | | | | |
| VREF Voltage | Over Temperature | 2.35 | 2.5 | 2.65 | V |
| Line Regulation | VHUB = 4.5V to 9V | | 3 | 10 | mV |
| 3.3V Regulator | | | | | |
| V33 Voltage | T _J = 25°C, I _{LOAD} = 10mA | 3.2 | 3.3 | 3.4 | V |
| | 0mA to 100mA, 0°C to 125°C, VHUB = 4.5V to 9V | 3.165 | 3.3 | 3.435 | V |
| Short Circuit Current Limit | VHUB = 6V, Output shorted to Ground | 100 | 120 | 150 | mA |
| Pre-Regulator | | | | | |
| VREG Voltage | 0A to 2A, 0°C to 125°C, VFIL = 6V to 9V | 5.25 | 5.5 | 5.7 | V |
| 5V Regulator | | | | | |
| V5A-D Voltage | T _J = 25°C, I _{LOAD} = 250mA, VREG = 5.5V | 4.85 | 5 | 5.15 | V |
| | 0mA to 500mA, 0°C to 125°C | 4.8 | 5 | 5.2 | V |
| Short Circuit Current Limit | VREG = 5.5V, Output Shorted to Ground | 500 | 600 | 750 | mA |
| Charge Pump | | | | | |
| Quiescent Output Voltage | T _J = 25°C, VFIL = 6V, ENA-D = 5V, ENHUB = 5V | 11 | 11.45 | 12 | V |
| | 0°C to 125°C, VFIL = 6V | 10.5 | 11.45 | 12 | V |
| Output Impedance | | | 9 | 15 | kΩ |
| Enable Inputs | | | | | |
| ENA-D Inputs - Guaranteed Low | | | | 0.7 | V |
| ENA-D Inputs - Guaranteed High | | 3 | | | V |
| Enable Inputs (cont.) | | | | | |
| ENHUB Input - Guaranteed Low | | | | 0.7 | V |

ELECTRICAL CHARACTERISTICS Unless otherwise specified, $T_J = 0^\circ\text{C}$ to 125°C for the UCC3831. $V_{FIL} = 6.5\text{V}$, $V_{HUB} = 5\text{V}$. $T_A = T_J$.

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|-------------------------------|----------------------------|-----|-----|-----|-------|
| ENHUB Input - Guaranteed High | | 3 | | | V |
| Overcurrent Signals | | | | | |
| Active Sink Current | $I_{OCX} = 100\mu\text{A}$ | | 140 | 500 | mV |

PIN DESCRIPTIONS

ENA-D: Separate enables pins for each of the four 5V supplies.

ENHUB: Enables the 3.3V output V33. Pulling this pin low disables V33.

GATE: Gate drive for an external NMOS used to regulate the 5.5V VREG supply. Minimum available drive is 11V.

GND: All 6 GND pins must be tied to the system ground. In addition to serving as electrical conductors, these 6 pins are heat sinks. Refer to the Packaging Device Temperature Management guide in the Packaging section of the Unitrode Databook.

OCA-D: Open drain overcurrent indicator. OCA-D can be wire OR'ed by the user to create a single overcurrent indicator.

V5A-D: 5V regulated output with enable, 500mA (minimum) current limit, and overcurrent indicator.

V33: 3.3V regulator output. Enable when ENHUB is high. Current limit is 100mA minimum.

VDRIVE: Internal charge pump voltage is brought out for external decoupling. Nominal voltage is between 11V and 13V. No external loading permitting. Decouple with at least $0.001\mu\text{F}$ capacitor.

VFIL: Bias supply for all four of the 5V regulators. VFIL voltage must be between 6V and 9V.

VHUB: Supply for the 3.3V USB controller power supply and bandgap reference.

VREF: Internal 2.5V reference is brought out for external decoupling only. Decouple with $0.01\mu\text{F}$ capacitor.

VREG: Regulated to 5.5V by means of an external NMOS. 2 pins supply up to a total of 2.5A to the four 5V bus voltages (V5A, V5B, V5C, V5D).

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| UCC3831DW | OBSOLETE | | UTR | | | TBD | Call TI | Call TI |
| UCC3831DWP | OBSOLETE | SOIC | DW | 28 | | TBD | Call TI | Call TI |
| UCC3831DWPTR | OBSOLETE | SOIC | DW | 28 | | TBD | Call TI | Call TI |
| UCC3831N | OBSOLETE | PDIP | N | 28 | | TBD | Call TI | Call TI |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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